

**SeamTek® Type 10 Seamless Resinous Flooring
Section- _____****Part 1 - GENERAL****1.01 RELATED DOCUMENTS**

- A. Drawings and general provisions of Contract, including General and Supplemental Conditions and Division 1 Specification sections apply to work of this section.

1.02 WORK INCLUDED

- A. Provide materials, labor and equipment required to prepare designated floor area
- B. and install floor system as shown on the drawings.
Related Work:
 - 1. Section 03300: Concrete Work, for concrete substrate.
 - 2. Section : Plumbing, drains.
 - 3. Section 07000: Sealants, silicone sanitary and USDA sealants.

1.03 QUALITY ASSURANCE

- A. Manufacturer: Obtain all materials required for this Section from a single manufacturer.
- B. Contractor: Shall have a minimum of 10 years experience in the installation of seamless floorings and be approved in writing by the specified manufacturer.

1.04 WARRANTY

Furnish manufacturer's written warranty on seamless flooring in conjunction with the selected flooring system for period of two years after installation, warranting against loss of bond and wear through to concrete substrate (through normal wear and use). Warranty shall be single source from the manufacturer, including material and labor.

1.05 DELIVERY, HANDLING AND STORAGE

- A. Deliver materials in manufacturer's unopened, undamaged containers, clearly marked with the following:
 - 1. Product Name
 - 2. Manufacturer's Name
 - 3. Resin or Hardener Designation
 - 4. Mix Ratio of Resin and Hardener
- B. Handle materials in a safe and proper manner to avoid damage or spill.
- C. Inspect direct job site deliveries to verify correct material and quantities are received in good condition.
- D. Replace, at no cost to the owner, materials that are found to be defective in manufacturing or damaged in transit, handling or storage.
- E. Store materials per manufacturer's instructions and as follows:
 - 1. Seals and labels shall be intact and legible.
 - 2. Temperature of storage area shall be maintained between 60°F and 85°F.
 - 3. Do not use materials which have been stored for a longer period of time than the manufacturer's maximum recommended shelf life.

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1.06 JOB SITE CONDITIONS

- A. Pre-Installation conference shall be required with General Contractor, Owners Representative, Flooring/Lining Contractor and Manufacturer's Representative to review the following:
 - a. Evaluate slab and side wall conditions and extent of repairs necessary for Contractor to begin normal preparation and installation of seamless flooring.
 - b. Evaluate detail conditions at all penetrations, terminations, perimeter and drain locations. Detail problems shall be documented and resolved prior to floor installation. Walls shall be "bug-hole" free.
 - c. Test concrete sub-floors to verify that slab moisture content does not exceed manufacturer's recommendations for vapor transmission.
 - d. Review job site conditions, including temperature, power, and lighting. Such problems shall be documented and resolved prior to floor installation.
- B. All drains must be in working condition.
- C. Job area shall be free of other trades during floor installation, and for a period of 48 hours upon completion.
- D. General Contractor shall provide adequate ventilation by use of fans or other devices.
- E. General Contractor shall maintain lighting at final end use levels during the installation.
- F. General contractor shall ensure that leaks from pipes and other sources are
- G. corrected prior to flooring installation.
- H. General Contractor shall provide minimum substrate temperature of 60° F and ambient temperatures between 65° and 80° F; relative humidity shall be below 75% during floor installation and until final acceptance.

1.07 CURING, CLEAN UP AND PROTECTION

- A. Cure final system in accordance with manufacturer's recommendations.
- B. Clean up work area, removing all equipment, materials and trash.
- C. General contractor shall provide temporary protection from construction traffic and other trades prior to final acceptance by the owner.

Part 2 - PRODUCTS

2.01 MATERIALS: **(NOTE TO SPECIFIER) The TekCoat system is actually a custom design based on specific objective. The system outlined below is a typical epoxy TekCoat system.**

- A. Systems Overview:

Floor system shall be LSP's SeamTek® Type 10 (TekCoat) applied at a minimum finish thickness of 15 mils. All surfaces to receive the system shall be smooth and free of surface imperfections, the repair of which is not included in this specification or the responsibility of the flooring Contractor unless otherwise clearly specified. Additional sloping to drains within the floor shall be only as specified by the design professional in specific drawing details relevant to this specification. The floor system shall consist of a base primer coat of moisture vapor retardant resin applied at 10 mils on flat surfaces and at appropriate hang thickness on vertical surfaces. The primer will be sealed by a 100% solids epoxy seal coat applied at 10 mils. Apply successive coats of the resin if necessary to assure that the final surface is pin hole free.

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Part 3 - EXECUTION

3.01 Surface Preparation

- A. Prepare new concrete to "open" surface pores by means of mechanical abrasion, removing contaminants and bond breaking substances, including but not limited to dust, latencies, curing compounds, coatings, sealers, oil and grease. Any contaminants that may affect bond strength must be removed in accordance with manufacturer's recommendations.
- B. For pits in rehab mode: Mechanically remove delaminated or deteriorated concrete.
- C. Areas to be patched shall be saw cut to minimum 1/2" depth at perimeters and keyed to existing concrete.
- D. At drains and all areas where the lining terminates, install a key way in the substrate to provide a thickened transition at that point.
- E. In areas where existing coatings or floors have been determined by mutual consent of the contractor and the end user to be of sufficient condition to remain in place, such coatings become the substrate for the purpose of preparation instructions. In such cases the substrate, being sound, shall be prepared by means of mechanical abrasion of 100% of the bonding surface.
- F. Cracks and Non-Expansion Joints
 - 1. Clean and fill cracks and non-expansion joints less than 1/16" wide with STI semi-rigid epoxy.
 - 2. Rout, saw out or rake-out cracks and non-expansion joints greater than 1/16" wide after surface preparation, and fill with STI semi-rigid epoxy. Filled cracks or joints shall have fiberglass cloth or flexible urethane "Band-Aid" applied over them to further inhibit cracks from telegraphing through the lining.

3.02 APPLICATION

- A. Apply each component of flooring system per manufacturer's installation instructions, including mixing and application.
- B. Cure flooring materials in compliance with manufacturer's directions.
- C. Install dust barriers at points between phases to eliminate dust contamination in adjacent areas.

3.03 CLEANING AND PROTECTION:

- A. Cleaning: Remove all debris resulting from the flooring installation during the progress of the work.
- B. Protection: General contractor shall provide protection from other trades.